

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Donald Malcolm MacIntyre

Application No.: 09/045,507

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

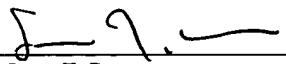


Group Art Unit: 2814

Examiner: Douglas A. Wille

**RESPONSE TO FINAL REJECTION
MAILED FEBRUARY 12, 2004**121 Spear Street, Suite 290
San Francisco, CA 94105
(415) 512-1312Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope, addressed to: Commissioner for Patents, Washington, DC 20231 on August 11 2004.

STALLMAN & POLLOCK LLP
Dated: 08/11/2004 By: 
Lana T. Brenner

Sir:

In response to the Final Rejection mailed February 12, 2004, please amend the above-identified application as follows:

Amendments to the claims are reflected in the Listing of Claims that begins on page 2 of this paper.

Remarks begin on page 6 of this paper